

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR

Automotive Grade, Soft Termination Type (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)							

SAM	SAMWHA CAPACITOR CO., LTD.							
Prepared by Checked by Approved by								
2185	7/-	gros-						

2023. 02. 10.

SAMWHA CAPACITOR CO., LTD.

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Contents

General Description	1/9
Specifications and Test Methods	3/9
Packing	7/9
Caution	- 8/9
Note	. 9/9

STANDARD NO SW - Q - 01A Enactment: MULTILAYER CERAMIC CAPACITOR Feb. 1, 2010 Page 1 / 9 Automotive Grade, Soft Termination Type

*Caution: Reflow soldering only

1. General Code

(1) Type Designation

CQ	<u>3216</u>	<u>X7R</u>	<u>475</u>	<u>K</u>	<u> 250</u>	A	<u>R</u>	Ī
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Automotive Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X7R	-55 to +125℃	±15%
Class	X7S	-55 to +125℃	±22%
Class II	X7T	-55 to +125℃	+22% ~ -33%
	X6S	-55 to +105℃	±22%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %

Code	Tolerance		
G	± 2.0 %		
J	± 5 %		
K	± 10 %		
М	± 20 %		

6) Voltage Code

Code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rated	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

N: Nickel-Tin Plate

A: Nickel-Tin Plate -> Soft Termination Type

8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

9) Thickness option

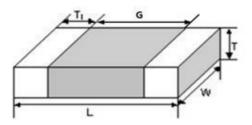
Thickne	Thickness (mm)		Thickne	Thickness (mm)		
t	Tol(±)	Code	t	Tol(±)	Code	
0.50	0.10	Blank	1.35	0.20	Н	
0.60	0.10	А	1.60	0.30	I	
0.80	0.15	В	1.80	0.30	J	
0.85	0.15	В	2.00	0.30	K	
1.00	0.15	Е	2.50	0.30	L	
1.10	0.15	Е	2.80	0.30	M	
1.15	0.20	Е	3.20	0.40	N	
1.25	0.20	Е	5.00	0.50	0	
1.30	0.20	E				

2. Temperature Characteristics

See Page 6/9 (No.21)

3. Constructions and Dimensions

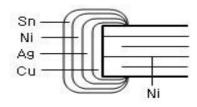
(1) Dimensions



		Dimension								
Size Code	EIA Code	Length			Wi	dth				
		L	Tol(-)	Tol(+)	W	Tol(±)	T1(min.)	G(min.)		
1005	0402	1.00	0.05	0.10	0.50	0.10	0.15	0.30		
1608	0603	1.60	0.15	0.20	0.80	0.15	0.20	0.50		
2012	0805	2.00	0.20	0.30	1.25	0.20	0.20	0.70		
3216	1206	3.20	0.50	0.50	1.60	0.30	0.30	1.20		
3225	1210	3.20	0.50	0.50	2.50	0.30	0.30	1.00		
4520	1808	4.50	0.50	0.50	2.00	0.30	0.30	1.00		
4532	1812	4.50	0.50	0.50	3.20	0.40	0.30	2.20		
5750	2220	5.70	0.30	0.70	5.00	0.50	0.30	3.20		

(Unit: mm)

(2) Construction of Termination



SW - Q - 01A 3 / 9

Specifications and Test Methods (For Automotive Applications)

No	AEC-Q200		Spe	cification	Test Methods and Conditions			
No.	Test Item		Class	Class	Test Methods and Conditions			
1	Pre-and Post- Electrical Test				-			
		Appearance	No defects which may affect	performance				
	I Ii ada	Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	T			
2	High Temperature Exposure	Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≥400+20×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Temperature: Max. operating temperature±3 °C Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than $10,000M\Omega$ or 500Ω (Whichever is smaller)	P·F (*50Ω·F)				
		Appearance	No defects which may affect	performance	Perform the 1000 cycles according to the four heat treatments			
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0%	listed in the following table. Let sit for 24±2 hours at room temperature, then measure.			
3	Temperature		30pF min.:Q≧ 1000	Rated Voltage 16V min.: 0.05 max.	Step 1 2 3 4			
Ū	Cycling	Q/D.F.	30pF max.:Q≧400+20×C C: Nominal Capacitance (pF)	10V: 0.075 max. *0.2 max.	Temp.($^{\circ}$ C) -55+0/-3 25±2 125+3/-0 25±2 Time(min) 15±3 1 15±3 1			
		I.R.	More than $10,000M\Omega$ or 500Ω (Whichever is smaller)	P-F (*50Ω-F)	Initial measurement Perform the initial measurement according to Note 1 for Class			
4	Destructive Physical Analy	ysis	No defects or abnormalities		Per EIA-469			
		Appearance	No defects which may affect	performance	Temperature: 25~65°C, Humidity: 80~98%			
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	Cycle Time: 24 hrs/cycle, 10 cycles Let sit for 24±2 hours at room temperature, then measure. 80-98% 80-98%			
5	Moisture Resistance	Q/D.F.	30pF min.: Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	65 66 55 55 56 2 44 2 44 2 35 2 30 8 30 8 30 8 30 8 30 8 30 8 30 8 30 8			
		I.R.	More than 10,000M Ω or 500 Ω (Whichever is smaller)	P·F (*50Ω·F)	15 10 5 0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 2 Time (hrs)			
		Appearance	No defects which may affect	performance				
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature : 85±3 ℃ Humidity : 80~85%			
6	Humidity Bias	Q/D.F.	30pF min.: Q≥200 30pF max.: Q≥100+10/3×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Applied Voltage: Rated Voltage and 1.3+0.2/-0V Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than 1,000M Ω or 50 Ω -F (Whichever is smaller)	(*5Ω·F)	The charge/discharge current is less than 50mA.			
		Appearance	No defects which may affect	performance	Tamanahan May and the tamanahan and an			
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature: Max. operating temperature±3°C Applied Voltage: Rated Voltage × 200% (*150%) Maintenance Time: 1000+48/-0 hrs			
7	7 High Temperature Operating Life	Q/D.F.	30pF min.:Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Let sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than 1,000M Ω or 50 Ω ·F (Whichever is smaller)	(*5Ω·F)	measure.			

SW - Q - 01A 4 / 9

Specifications and Test Methods (For Automotive Application)

N.	AEC	-Q200	Specification			Took Mathada and Oorditions		
No.		Item	Class Class			Test Methods and Conditions		
8	External Visu	al	No defects or abnormalities			Visual inspection		
9	Physical Dime	Physical Dimension Within the specified dimensions				Using calipers		
		Appearance	No defects which may affect p	performance				
		Capacitance Change	Within the specified tolerance					
10	Resistance to Solvents	Q/D.F.	30pF min.: Q≥1000 30pF max.: Q≥400+20×C C: Nominal Capacitance (pF) More than 10,000MΩ or 500ΩF	16V: (10V: (*0.125 max.	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Per MIL-STD-202 Method 215		
		I.R.	(Whichever is smaller)					
		Appearance	No defects which may affect p	performance				
		Capacitance Change	Within the specified tolerance			Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)		
11	Mechanical Shock Q/D.F.		30pF min.:Q≧1000 30pF max.:Q≧400+20×C C: Nominal Capacitance (pF)	16V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	Test Pulse Wave form : Half-sine Duration : 0.5ms Peak value : 1,500G		
		I.R.	More than $10,000M\Omega$ or 500Ω -F (Whichever is smaller)	- (*50Ω·F)		Velocity change : 4.7m/s		
		Appearance	No defects or abnormalities					
		Capacitance Change	Within the specified tolerance	D	2005	The specimens should be subjected to a simple harmonic motion		
12	Vibration	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20×C C: Nominal Capacitance (pF)	16V: (10V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	having a total amplitude of 1.5mm. The entire frequency range of 10 to 2,000 Hz and return to 10 Hz should be traversed in 20 minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times).		
		I.R.	More than 10,000M Ω or 500 Ω -F (Whichever is smaller)	*0.125 max. = (*50Ω·F)				
		Appearance	No defects which may affect p	performance				
		Capacitance Change	Within the specified tolerance			Temperature (Eutectic solder solution) : 260±5°C		
13	Resistance to Solder Heat	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20×C C: Nominal Capacitance (pF)	16V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	Dipping Time: 10±1s Let sit for 24±2 hours at room temperature, then measure. Initial measurement Perform the initial measurement according to Note 1 for Class II.		
		I.R.	More than $10,000M\Omega$ or 500Ω -F (Whichever is smaller)					
		Appearance	No defects which may affect p	performance		Perform the 300 cycles according to the two heat treatments listed		
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±15.0%		in the following table. Transfer Time : 20sec. max.		
14	Thermal Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20×C C: Nominal Capacitance (pF)	16V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	Let sit for 24±2 hours at room temperature, then measure. Step 1 2 Temp.(°C) -55+0/-3 125+3/-0 Time(min.) 15±3 15±3		
		I.R.	More than 10,000M Ω or 500 Ω -F (Whichever is smaller)	·		Initial measurement Perform the initial measurement according to Note 1 for Class II.		

SW - Q - 01A 5 / 9

Specifications and Test Methods (For Automotive Application)

	AEC-		,	itomotive Application)					
No.	No. Test Item		Class	Class	Test Methods and Conditions				
	1000		No defects which may affect pe						
		Capacitance Change	· · ·	T TOT HIGHE					
15	ESD	Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20×C C: Nominal Capacitance (pF)	Q≥400+20×C 16V: 0.035 max. Capacitance (pF) 10V: 0.05 max.					
			More than 10,000MΩ or $500Ω$ -F	*0.125 max. (*50Ω·F)					
	I.R.		(Whichever is smaller)	,					
16 Solderability			95% of the terminations is to be s	oldered evenly and continuously.	 (a) Preheat at 155 °C for 4 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C. (b) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C. (c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 120±5 seconds at 260±5 °C. 				
		Annearance	No defects or abnormalities		The capacitance/Q/D.F. should be measured at 25 ℃ at the				
		Capacitance			frequency and voltage shown in the table.				
		Change	Within the specified tolerance		Class Capacitance (C) Frequency Voltage				
		Change		Rated Voltage 50V: 0.025 max.	Class I				
17	Electrical Characteriza- tion	Q/D.F. 30p	30pF min.:Q≥1000 30pF max.:Q≥400+20×C C: Nominal Capacitance (pF)	25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	· Initial measurement Perform the initial measurement according to Note1 for Class II · Measurement after test Take it out and set it for 24±2 hours (Class II) then measure				
		I.R. at 25℃	More than 100,000M Ω or 1,000 Ω -F (Whichever is smaller)	More than 10,000M Ω 500 Ω ·F (*50 Ω ·F) (Whichever is smaller)	Should be measured with a DC voltage not exceeding rated				
		I.R. at 125℃	More than 10,000M Ω or 100 Ω ·F (Whichever is smaller)	More than 1,000M Ω or 10 Ω -F (*1 Ω -F) (Whichever is smaller)	voltage at 25℃ and 125℃ for 2 minutes of charging.				
		Voltage	No dielectric breakdown or mecha	anical breakdown	Applied 250% of the rated voltage for 1~5 seconds				
		Appearance	No defects which may affect pe	erformance	The charge/discharge current is less than 50mA. Apply a force in the direction shown in the following figure for 60±5 seconds. Support Solder Chip Printed circuit board before testing				
18	Board Flex	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance	Printed circuit board under test Flexure for Class I: 3mm max. for Class II: 3mm max. - Reflow soldering only				
		Appearance	No defects which may affect pe	erformance	Apply 18N ¹⁾ force in parallel with the test jig for 60±1 seconds.				
19	Terminal Strength		Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance	¹⁾ 10N for 1608(EIA:0603) size 2N for 1005(EIA:0402) size				
	I.	Juliango	(Transmitter to larger)		2.1.101 1000(211.0702) 3120				

SW - Q - 01A

6 / 9

Specifications and Test Methods (For Automotive Application)

	D. AEC-Q200 Test Item		Specification											
No.			Class			Class II	Test Methods and Conditions							
			The chip endure following force.			,	Apply a force as shown in the following figure. (i) Chip Length: 2.5mm max. (ii) Chip Length: 3.2mm min.							
			Chip Length	Thickness	. ,		Beam Speed : 0.5mm/s		,	Beam Speed : 2.5mm/s				
20	Beam Load		2.5mm max.	T≤0.5mm		8N		Boam opood : 2.5mm/6						
-	Joann Load	Deam Edau		T>0.5mm		20N	1 4							
			3.2mm min.	T<1.25n		15N	V	Iron Board						
			T		5	54.5N		0.6						
	Capacitance Temperature	Capacitance Change Temperature Coefficient	0±30 ppm/°C		X7S :	: Within ±15% : Within ±22% : Within ±22% : Within ±22% ~ -33%	(i) Class I The temperatumeasured in sequentially from the specific sequential of the sequential of the capacitan between the model of the sequential of the	tep 3 as a om step cified tole ce drift is naximum	a reference through 5 rance for the calculated and minim	e. When cy i, the capa he temper I by dividir um measu	ycling the acitance stature coeing the diffured value	temperatu hould be efficient. erences	ture	
21	Characteris-						Step	1	2	3	4	5		
							Temp.(°C)	25±2	-55±3	25±2	125±3	25±2		
		Capacitance Drift	Within ±0.2% or ±0. (Whichever is large	•			(ii) Class II The ranges of over the temporal initial measure Perform the ir	erature ra	ange from -	55°C to 12	25℃.			

In the case of "*" is specifications for "Thin Layer Large Capacitance Type"

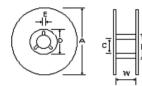
Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10°C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change."

Packing

- (1) Bulk Packing
 - 1 1000 pcs per polybag
 - 2 5 polybags per inner box
 - 3 10 inner boxes per out box
- (2) Reel Packing
 - ① 8~10 reels per inner box
 - 2 6 inner boxes per out box
- (3) Reel Dimensions

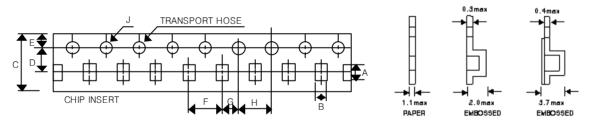


							(Uı	nit : mm)
Mark	Size Code	EIA Code	Α	В	С	D	Е	w
7 " Reel	1005~3225	0402~1210	Ф178±2	Ф 50Min	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5
	4520~4532	1808~1812	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " Reel	1005~3225	0402~1210	Ф330±2	Φ70Min	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5

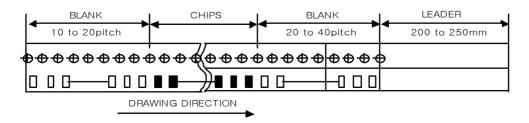
(4) Number of Package

Size Code	FIA Code	7"	13"		
Size Code	EIA Code	Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		
4520	1808	1,500 ~ 3,000	_		
4532	1812	500 ~ 1,000	1,500 ~ 5,000		

(5) Tape Dimensions



Size Code	EIA Code	А	В	С	D	Е	F	G	Н	J
1005	0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
1608	0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
2012	0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3216	1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3225	1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4520	1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4532	1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



Caution

▶ Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

(1) Temperature: 25°C ± 10°C

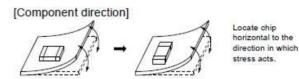
(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials Never use materials mentioned below in MLCC products regulated this document.

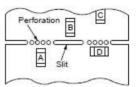
Pb, Cd, Hg, Cr⁺⁶, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

► Mounting Position

Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.



[Chip Mounting Close to Board Separation Point]



Chip arrangement Worst A-C- (B, D) Best

▶ Reflow Soldering

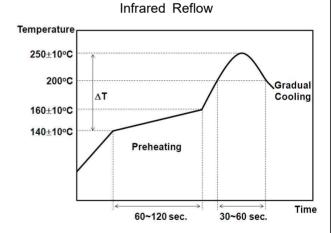
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference(△T) within the range recommended in Table 1.

Table 1

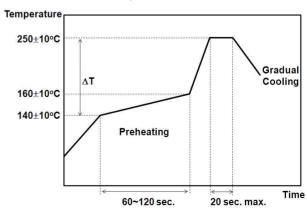
Size code (EIA Code)	Temperature Difference
1005~3216 (0402~1206)	△T≤190°C
3225 (1210)	△T≤130°C

3. Capacitors designated as for only reflow soldering must not apply to wave soldering.

Recommended Reflow Soldering Profile for Lead Free Solder



Vapor Reflow



Note

► 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs (Typically represented by X7R temperature characteristic of which main composition is BaTiO₃)

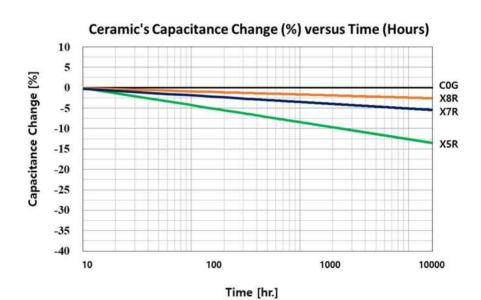
'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

where,

Ct : Capacitance value, t hours after the start of 'aging'
 C24 : Capacitance value, 24 hours after its manufacture
 k : Aging constant (capacitance decrease per decade-hour)

t : time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately $120\,^{\circ}$ C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at $150\,^{\circ}$ C for about 1 hour.